



PRODUCT INFORMATION

Customer :

Device : Device ID :

Die Size : Wafer Material :

Package Type: **8L SOIC NB EPAD** No. of Wires :

MATERIAL INFORMATION

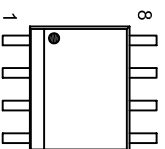
Leadframe : **A194 with spot Ag** Exposed Pad Size : **95x130 mils**

Epoxy : Wire size :

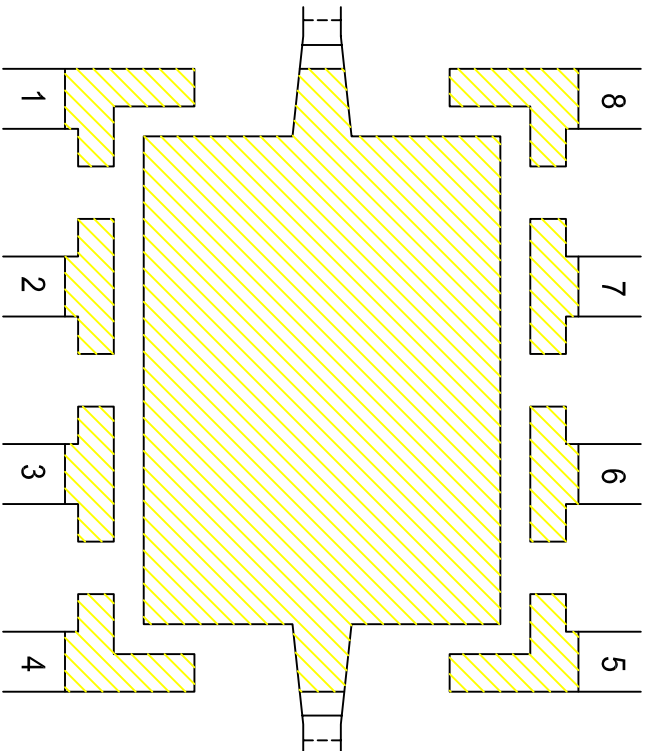
Molding Compound : Lead Finish :

MARKING INSTRUCTION

TOP : BOTTOM : n/a



BONDING DIAGRAM NO.



REF. BONDING DIAGRAM NO.

SCALE
not to scale

DRAWN BY: REVIEWED BY :

REVISION NO. APPROVALS

REV. #	DESCRIPTION	ECN #	DEPT	APPROVALS	DATE
			CUST		
			QSM		
			QC		
			MFG		

SPECIAL INSTRUCTIONS:

